

| | DBs |
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| 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB |
| 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB |
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| | Ref # | Search Text |
|-----------|--------------|--|
| 17 | S17 | S5 same S6 |
| 18 | S18 | S8 and S16 and S17 |
| 19 | S19 | ("4742385" "4827082" "5027191" "5311402").PN. |
| 20 | S20 | ("2005/0189632").URPN. |
| 21 | S21 | ("4603345" "5032894" "5281852" "5324687" "5401688" "5410451" "5448511" "5459641" "5552963").PN. |
| 22 | S22 | ("5776797").URPN. |
| 23 | S23 | ("5133495" "5229916" "5281852" "5394303" "5397916" "5582326" "5679977" "5682061" "5714405" "5776797" "5801446" "5885549" "5895970").PN. |
| 24 | S24 | (bond\$3 seal\$3) near6 (die substrate S3) |
| 25 | S25 | S5 with S24 |
| 26 | S26 | S7 same S25 |
| 27 | S27 | S2 same S25 |
| 28 | S28 | S25 with (via cavity opening) |
| 29 | S29 | S2 same S28 |
| 30 | S30 | encapsulant near4 filler |
| 31 | S31 | (silicone or polymer) with S30 |
| 32 | S32 | S31 and (@ad<"20040301" @rlad<"20040301") |
| 33 | S33 | S31 same glob |

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| 20 | USPAT |
| 21 | US-PGPUB; USPAT; USOCR |
| 22 | USPAT |
| 23 | US-PGPUB; USPAT; USOCR |
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| 1 | S1 | ("seal\$3encapsulat\$3").PN. |
| 2 | S2 | seal\$3 encapsulat\$3 |
| 3 | S3 | ((S1 adj2 "D") or (three near3 dimension\$3)) near6 ((metal near3 bond\$3 near4 ("ic" or (integrated near3 circuit))) or (bond\$3 near4 ("ic" or (integrated near3 circuit))) or ("ic" or (integrated near3 circuit)))) |
| 4 | S4 | connector (control\$3 near3 collaps\$4 near3 chip) "C4" (solder near3 (ball bump)) |
| 5 | S5 | (contact near3 pad) (copper near3 (contact or pad)) |
| 6 | S6 | (bond\$3 seal\$3) near6 (die substrate) |
| 7 | S7 | S5 with S6 |
| 8 | S8 | S2 same S3 |
| 9 | S9 | S2 with S3 |
| 10 | S10 | die substrate |
| 11 | S11 | die substrate wafer |
| 12 | S12 | S4 with S10 |
| 13 | S13 | S4 with S11 |
| 14 | S14 | S13 and S9 and S7 |
| 15 | S15 | S13 and S9 |
| 16 | S16 | S4 same S11 |